L Number	Hits	Search Text	DB	Time stamp
1	0	microcircuit and package and stacking and pretested adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:51
2	0	package and stacking and pretested adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:52
3	0	package and pretested adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:52
4	2	pretested adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:54
5	5	pretested and microcircuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:57
6	19	pre-tested and circuit and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 10:58

L Number	Hits	Search Text	DB	Time stamp
1	43	circuit adj board and encapsulated and grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:22
2	34	IC and encapsulated and grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:35
3	0	20020100600.URPN.	USPAT	2002/08/06 08:26
4	1	microcircuit and encapsulated and grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:35
5	66	circuit and encapsulated and grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:39
6	5	("3370203" | "3577037" | "4151543" | "4363076" | "4398235").PN.	USPAT	2002/08/06 08:37
9	9	circuit and encapsulated and grinding and polishing and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:40
10	8	BGA and encapsulated and grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:42
11	3	("5304534" | "5373627" | "5847445").PN.	USPAT	2002/08/06 08:41
12	13	encapsulated and grinding and stacking and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:44
13	1	chip and encapsulated near grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:45
14	1	encapsulated near grinding and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:47

15	0	20010055856.URPN.	USPAT	2002/08/06 08:46
16	7	grinding and stacking and 438/460.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:55
17	4	grinding and stacking and 438/462.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:55
18	2	grinding and stacking and 438/465.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:57
19	1	"5646067".PN.	USPAT	2002/08/06 08:56
20	0	20010055856.URPN.	USPAT	2002/08/06 08:57
21	178	grinding and stacking and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 09:25
22	6	("4750090" | "5657537" | "5699234" | "5739578" | "5844168" | "6290540").PN.	USPAT	2002/08/06 08:59
23	14	("4237522" | "4254446" | "4783695" | "4835704" | "4894115" | "4933042" | "5019946" | "5111278" | "5161093" | "5279029" | "5285571" | "5347928" | "5466634" | "5502667").PN.	USPAT	2002/08/06 09:01
24	40	("2907926" | "3029495" | "3065384" | "3070729" | "3139559" | "3152288" | "3370203" | "3746934" | "3748479" | "4520427" | "4525921" | "4551629" | "4612083" | "4638348" | "4646128" | "4706166" | "4727410" | "4764846" | "4801992" | "4818728" | "4833568" | "4862249" | "4868712" | "4879258" | "4894706" | "4901136" | "4902641" | "4926241" | "4956746" | "4983533" | "5016138" | "5019943" | "5019946" | "5051865" | "5064771" | "5071792" | "5091331" | "5162254" | "5266833" | "5347428").PN.	USPAT	2002/08/06 09:06
25	9	grinding and stacking and (albert et al).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 09:27

-	2	5086018.pn.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:59
-	2	6342398.pn.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	2	6060373.pn.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	3	5454160.pn.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	7	microcircuit and package and stacking and 29/$.ccls.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:59
-	71	5086018.URPN.		USPAT	2002/08/05 14:53
-	36	("4862245" | "4937656" | "4949161" | "5086018" | "5147815" | "5218168" | "5234866" | "5250840" | "5256598" | "5303120" | "5327009" | "5331200" | "5334873" | "5357139" | "5360992" | "5365113" | "5381036" | "5384488" | "5434106" | "5438478" | "5508565" | "5521426" | "5523617" | "5528075" | "5530292" | "5563443" | "5585667" | "5585668" | "5612259" | "5637915" | "5696665" | "5751057" | "5780925" | "5804870" | "5811875" | "6066515").PN.		USPAT	2002/08/05 14:56

-	84	("3246386" | "3290559" | "3313986" | "3377516" | "3403300" | "3515949" | "3535595" | "3614541" | "3671812" | "3746934" | "3949274" | "3959579" | "4017963" | "4116518" | "4116519" | "4288808" | "4288841" | "4364620" | "4371912" | "4379259" | "4394712" | "4398235" | "4571663" | "4574331" | "4631573" | "4638348" | "4638406" | "4642735" | "4688864" | "4696525" | "4698663" | "4706166" | "4761681" | "4770640" | "4821007" | "4841355" | "4868712" | "4884237" | "4924352" | "4953005" | "4956694" | "4996583" | "4996587" | "5016138" | "5025307" | "5031072" | "5041395" | "5043794" | "5058265" | "5086018" | "5107328" | "5128831" | "5140745" | "5155068" | "5198888" | "5222014" | "5231304" | "5239447" | "5241454" | "5281852" | "5311401" | "5313096" | "5343075" | "5343366" | "5369058" | "5373189" | "5384689" | "5397916" | "5420751" | "5426566" | "5446313" | "5479318" | "5481133" | "5493476" | "5499160" | "5514907" | "5552963" | "5561591" | "5566051" | "5586009" | "5605592" | "5612570" | "5615475" | "5723903").PN.	USPAT	2002/08/05 14:57
-	14	("3746934" | "4398235" | "4521828" | "4763188" | "4796078" | "4884237" | "4953060" | "4956694" | "5151559" | "5221642" | "5270492" | "5279029" | "5367766" | "5394010").PN.	USPAT	2002/08/05 14:58
-	4	29/841.ccls. and IC and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "PEM" and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "PEM"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "Plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:03

-		0	"Plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:03
-		0	"plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:04
-		0	plastic same encapsulant near microcircuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:04
-		14	plastic same encapsulant near circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:05
-		0	encapsulant near circuit and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:06
-		263	encapsulant and circuit and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:06
-		31	encapsulant and circuit and stacking and 174/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:07
-		13	encapsulant and circuit and stacking and 439/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:08
-		10	encapsulant and circuit and stacking and 228/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:08
-		134	encapsulant and circuit and stacking and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:09